



A Monte Carlo simulation model for surface evolution by plasma etching



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ABSTRACT

A Monte Carlo simulation model, i.e. sputtering etch model, was established with Monte Carlo method to simulate plasma etching induced surface morphology evolution. The surface morphology images and fractal exponents were obtained, with $\alpha=0.5$, $\beta=0.27$, $z=1.76$. Germanium samples were etched in SF₆ plasma and the post-etch surface was analyzed in order to compare with the model. The surface morphology images and fractal exponents by simulation describe the experimental results very well.

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1. Introduction

Plasma etching as an essential process of modern microelectronics has attracted considerable attention. So far, studies are mostly concentrated in the experimental study [1], including optimization of process parameters [2], exploration of new technology, related equipment design and optimization [3], and surface roughness of etching material [4,5]. Among them, the surface roughness of etching material has an important impact on device performance.

In spite of the fact that so much experimental work has been reported on plasma etching induced surface roughness, theoretical work on surface roughness evolution by plasma etching is still very limited except for a very few reports [6–8]. Zhao et al. have similar work on film growth [9,10]. They indicated that the dynamic roughening of polymer film is deeply affected by strong molecular interactions and relaxations of polymer chains [11]. Moreover, incident flux distribution, sticking coefficient, and surface diffusion

were accounted for in the growth process [12,13]. They also simulated the reactive ion etching [14–16]. Recently, Tang et al. use the Kinetic Monte Carlo (KMC) simulation to study the effect of the structure of fractal substrates on dynamic scaling behavior of the surfaces [17,18]. The etching model growing on diluted squares, the Sierpinski arrowhead and crab fractal substrates are simulated. The results show that the scaling exponents of the etching model growing on fractal substrate are determined by not only the fractal dimension but also the fractal structure. However, there are few studies on simulation of plasma etching process using Monte Carlo method. In this work, we established a sputtering etch model using Monte Carlo method to simulate the plasma etching process. In order to compare the simulation results with experimental ones, we also carried out etching experiments for germanium by SF₆ plasma. It was shown that the modeling results consist very well with the experimental results.

2. Sputtering etch model

There are a few models used for surface etching and growing simulation. We start with the reactive ion etching model, in which

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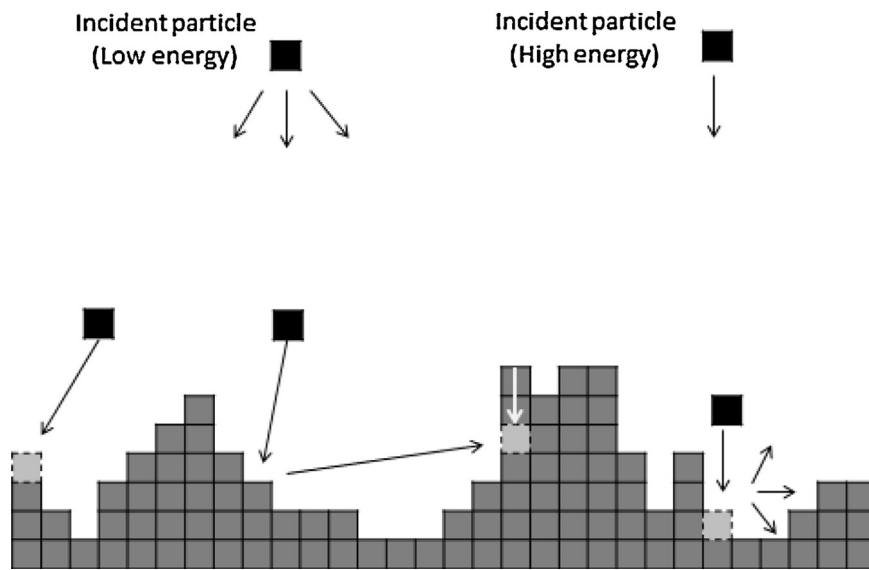


Fig. 1. Illustration of the Monte Carlo simulations for sputter etching.

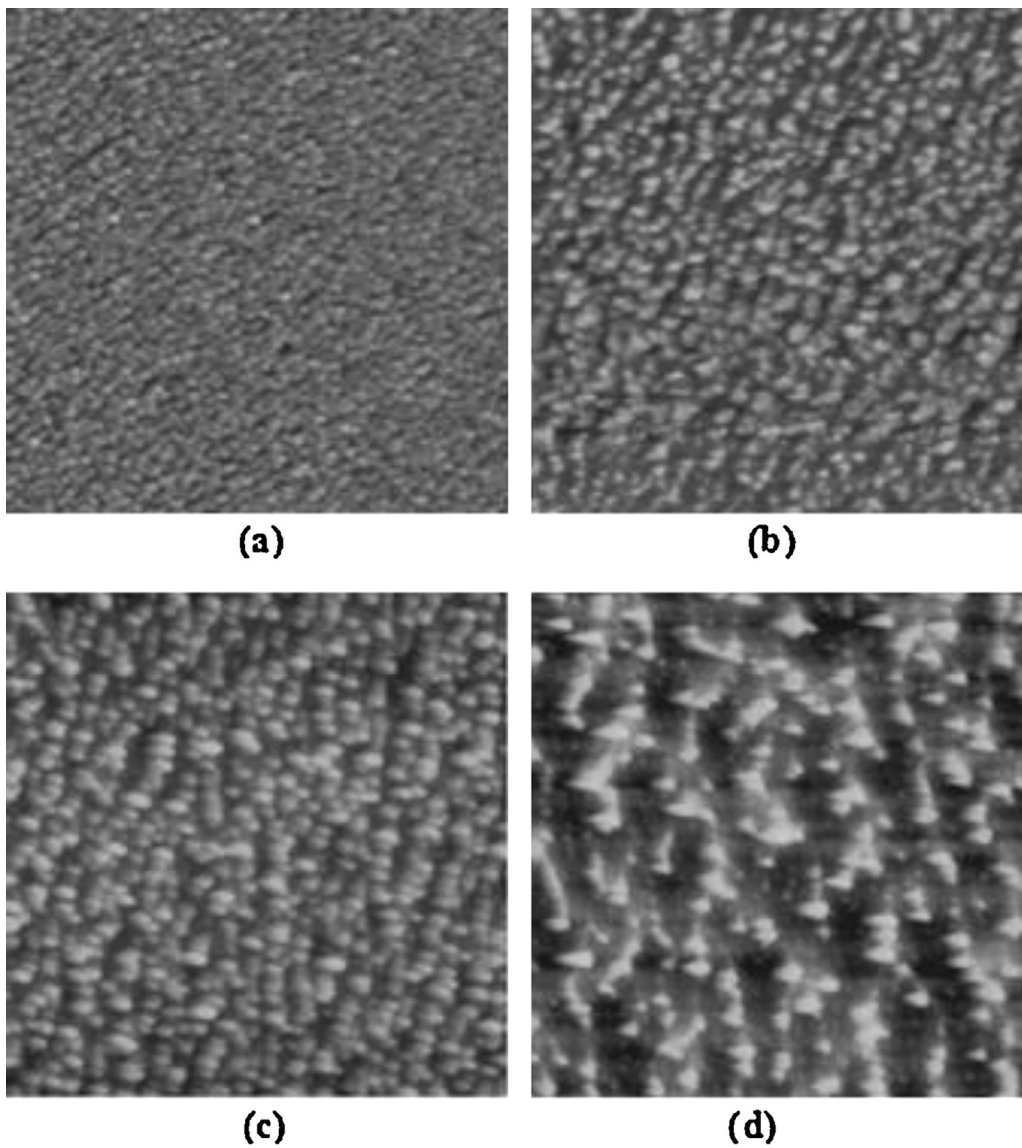


Fig. 2. Surface images of plasma etching for (a) $t = 60$ s, (b) $t = 120$ s, (c) $t = 180$ s, (d) $t = 360$ s. Light areas indicate high h , while dark areas indicate low h .

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